



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **YONEDA, et al.**

Group Art Unit: **2814**

Serial No.: **09/442,038**

Examiner: **N. Ha**

Filed: **November 17, 1999**

P.T.O. Confirmation No.: 5343

For: **DEVICE HAVING RESIN PACKAGE AND METHOD OF PRODUCING THE SAME**

REQUEST FOR RECONSIDERATION UNDER 37 CFR §1.111

Commissioner for Patents
Washington, D.C. 20231

March 31, 2003

Sir:

In response to the Office Action dated **December 4, 2002**, extended to **April 4, 2003** by a **one (1)** month Petition for Extension of Time, Applicants respectfully request reconsideration of the 35 USC §103(a) rejections of the claims under various combinations of **Hiroshi**, **Atsushi** and **Hosomi et al.**

In Applicants' response of July 24, 2002, we stated:

It should be noted that conductor 12 in **Hiroshi**, corresponding to the metallic film of the present invention, covers only the bottom surface of the resin projection. This is in contrast to the present invention as shown, for example, in Fig. 32, in which the films 113 cover both the bottom and side surfaces of the resin projections.

The Examiner has applied **Atsushi** for teaching this feature.

Applicants respectfully disagree. Although **Atsushi** discloses an optical semiconductor device in which connecting parts 6 projecting from the resin portion are completely covered by conductor pattern 2, there would be no motivation to apply this teaching to **Hiroshi** because conductor 12 is a flat plate covering the bottom of sealing resin 16 and the wiring board 10. There is no

Hiroshi

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